

## P-Channel 30V (D-S) MOSFET

### GENERAL DESCRIPTION

The ME2303S is the P-Channel logic enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where low in-line power loss are needed in a very small outline surface mount package.

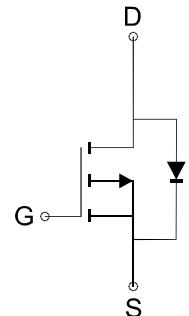
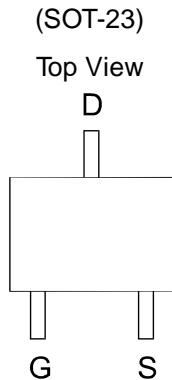
### FEATURES

- $R_{DS(ON)} \leq 75m\Omega @ V_{GS}=-10V$
- $R_{DS(ON)} \leq 100m\Omega @ V_{GS}=-4.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$

### APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- Load Switch
- DSC

### PIN CONFIGURATION



P-Channel MOSFET

**Ordering Information:** ME2303S(Pb-free)

ME2303S-G (Green product-Halogen free)

### Absolute Maximum Ratings ( $T_A=25^\circ C$ Unless Otherwise Noted)

Parameter	Symbol	Maximum Ratings	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current *  $T_A=25^\circ C$	$I_D$	-3.2	A
$T_A=70^\circ C$		-2.6	
Pulsed Drain Current	$I_{DM}$	-13	A
Maximum Power Dissipation  $T_A=25^\circ C$	$P_D$	1.3	W
$T_A=70^\circ C$		0.8	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C
Thermal Resistance-Junction to Ambient*	$R_{\theta JA}$	100	°C/W

\* The device mounted on 1in<sup>2</sup> FR4 board with 2 oz copper



**P-Channel 30V (D-S) MOSFET**
**Electrical Characteristics (TA=25°C Unless Otherwise Specified)**

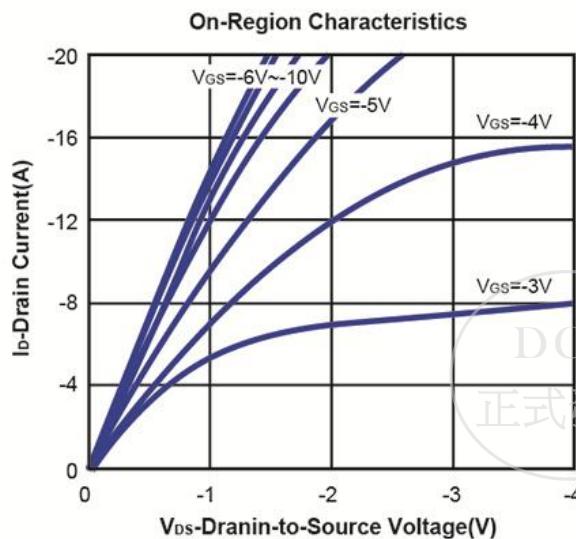
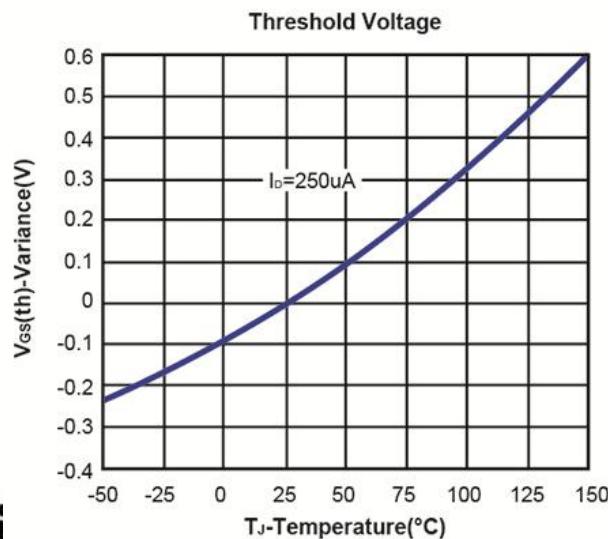
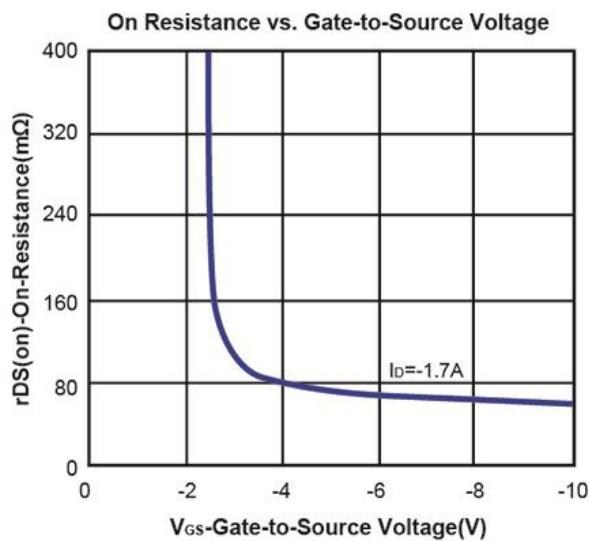
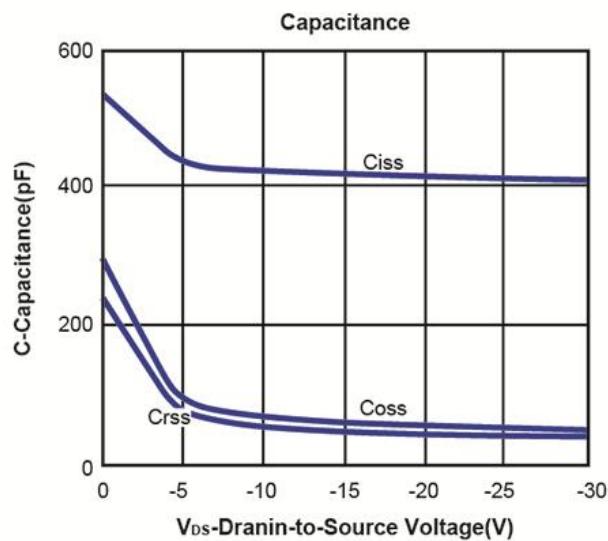
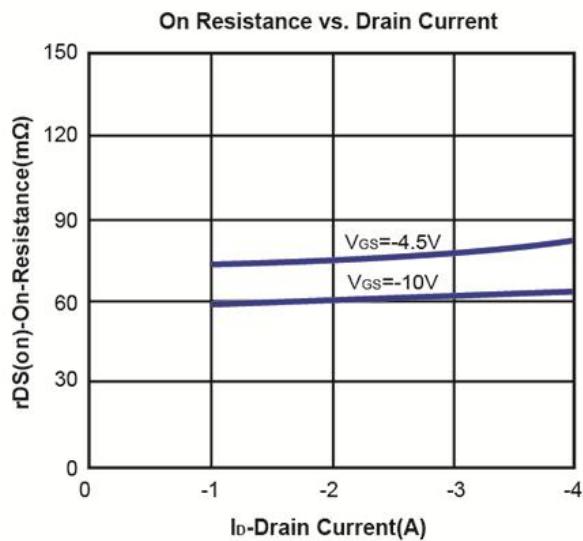
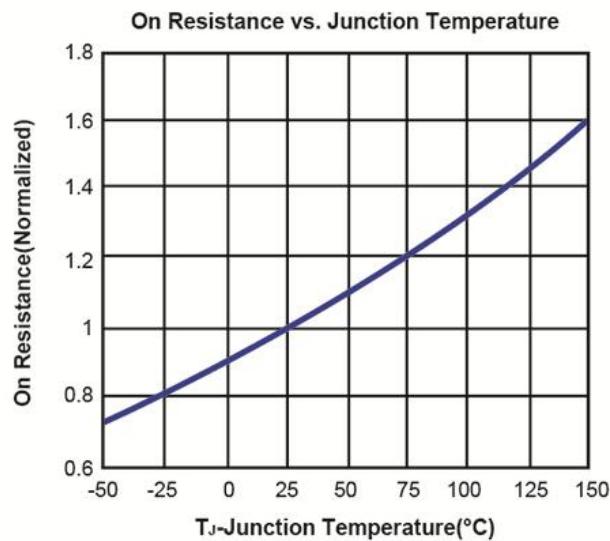
Symbol	Parameter	Limit	Min	Typ	Max	Unit
<b>STATIC</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250 μA	-30			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250 μA	-1		-3.0	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V			-1	μA
R <sub>D(S(ON))</sub>	Drain-Source On-Resistance <sup>a</sup>	V <sub>GS</sub> =-10V, I <sub>D</sub> = -1.7A		60	75	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> = -1.3A		75	100	
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =-1.25A, V <sub>GS</sub> =0V		-0.7	-1.4	V
<b>DYNAMIC</b>						
Q <sub>G</sub>	Total Gate Charge	V <sub>DS</sub> =-15V, V <sub>GS</sub> =-10V, I <sub>D</sub> =-1.7A		14		nC
Q <sub>G</sub>	Total Gate Charge			6.7		
Q <sub>GS</sub>	Gate-Source Charge	V <sub>DS</sub> =-15V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-1.7A		2.6		
Q <sub>GD</sub>	Gate-Drain Charge			2.1		
C <sub>ISS</sub>	Input Capacitance			416		pF
C <sub>OSS</sub>	Output Capacitance	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1MHz		56		
C <sub>RSS</sub>	Reverse Transfer Capacitance			46		
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DS</sub> =-15V, R <sub>L</sub> =15Ω R <sub>GS</sub> =6Ω, V <sub>GS</sub> =-10V I <sub>D</sub> =-1A		34.4		ns
t <sub>r</sub>	Turn-On Rise Time			18		
t <sub>d(off)</sub>	Turn-Off Delay Time			43.9		
t <sub>f</sub>	Turn-Off Fall time			5.6		

Notes: a. Pulse test; pulse width ≤ 300us, duty cycle≤ 2%

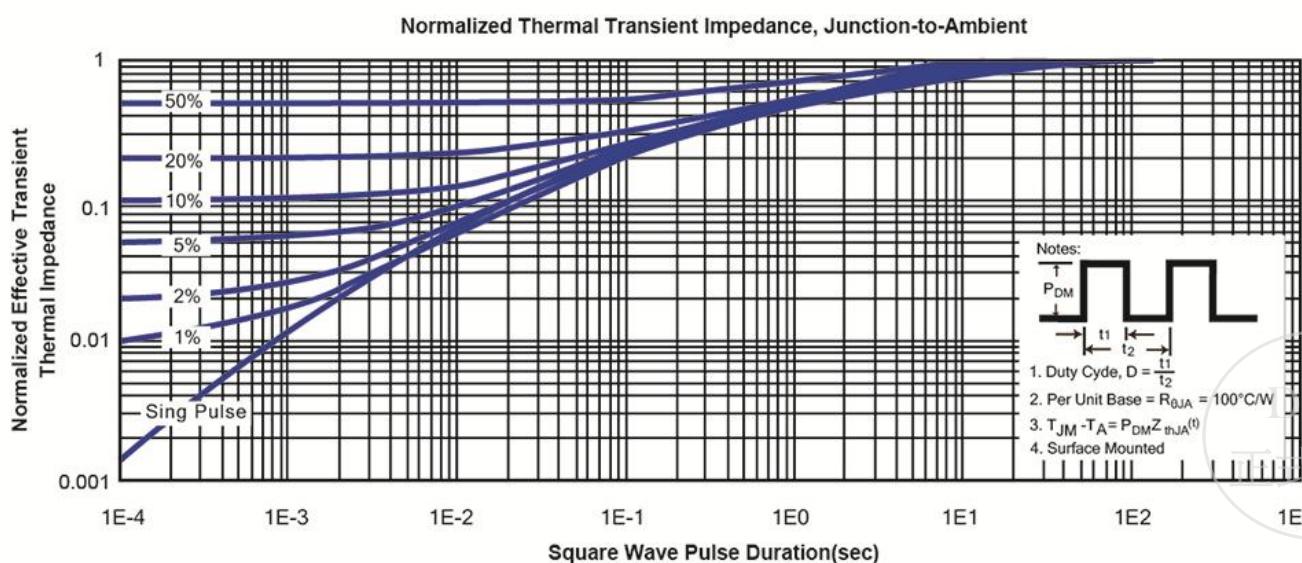
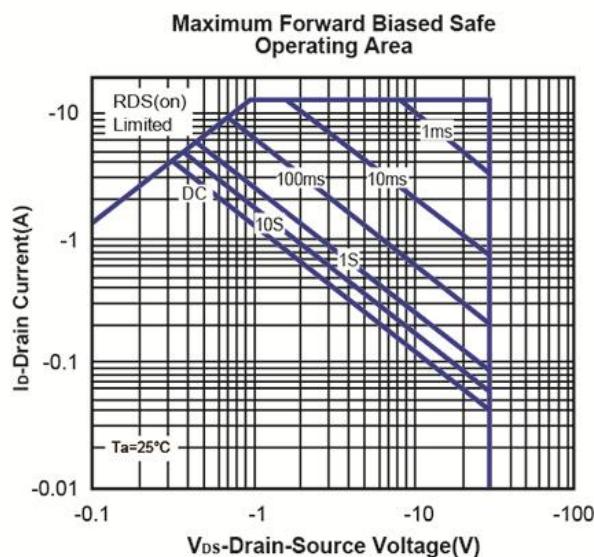
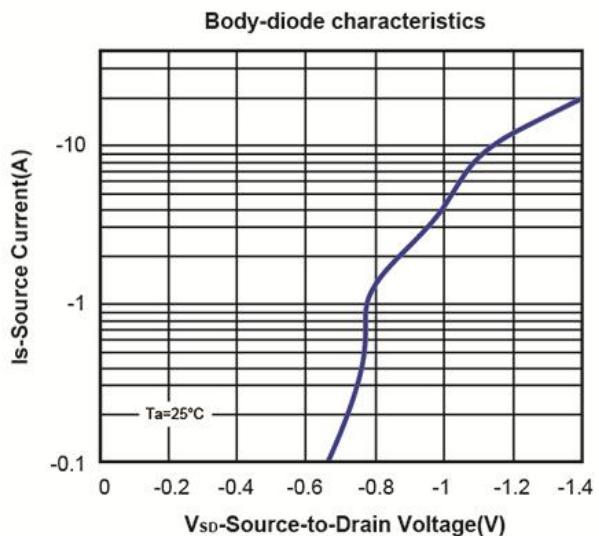
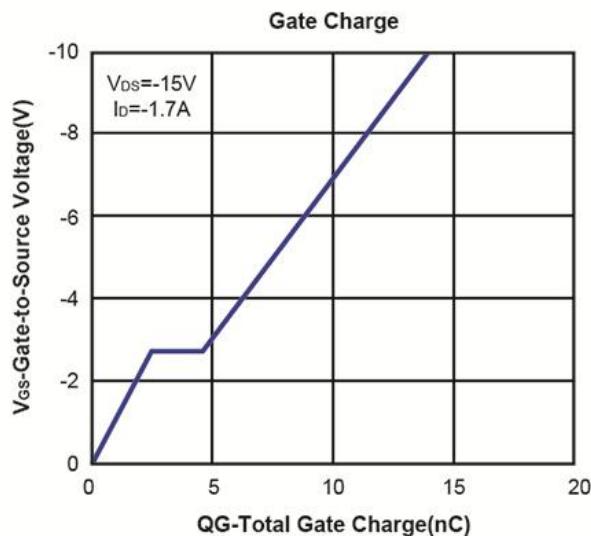
b. Matsuki Electric/ Force mos reserves the right to improve product design, functions and reliability without notice.



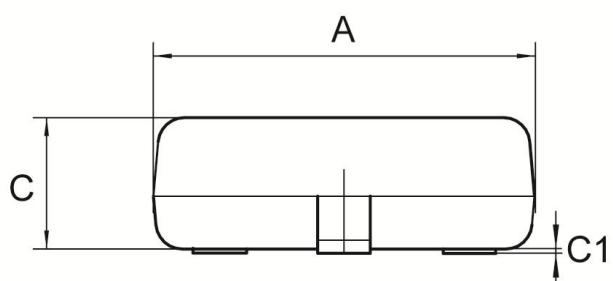
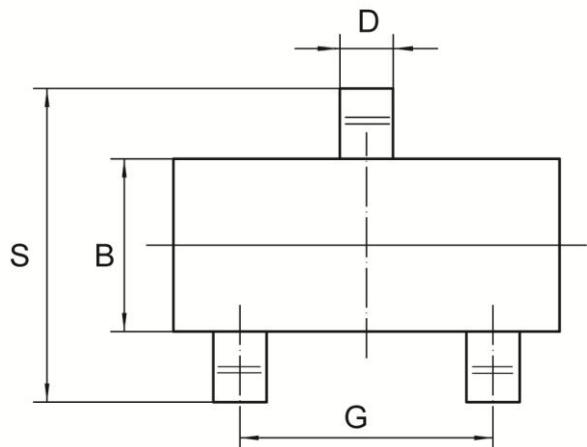
**Typical Characteristics ( $T_J = 25^\circ\text{C}$  Noted)**



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### SOT-23 Package Outline



Symbol	MILLIMETERS	
	MIN	MAX
A	2.8	3.0
B	1.2	1.4
C	0.9	1.1
C1	-	0.1
D	0.3	0.5
G	1.90 REF	
J	0.05	0.15
K	0.2	-
S	2.2	2.6

